

# ABSTRACT OF THE DISCLOSURE

In insert-molding a wiring board, at either one of a surrounding of a holding hole of the wiring board provided at a first plastic part and a second plastic part opposed thereto, 5 a hole side projected portion capable of being brought into contact with a bonding face of other thereof is provided, and the surrounding of the holding hole in the first plastic part and the second plastic part are bonded to each other by melting the hole side projected portion by applying ultrasonic wave 10 to bonding portions of the two plastic parts.